

Insulated Metallic Substrate PCB

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| PCB Type: | Singlesided |
| Min. drill endsize: | 1.0 mm |
| Min. tracksize: | 0.125 mm |
| Min. airgap | 0.125 mm |
| Soldermask: | Green / White / Black |
| Silkscreen: | White / Black |
| Surface: | HAL leadfree |
| Gap contour - copper: | 0.3 mm |
| Contour processing: | Routing |
| Copper thickness: | 0.035 mm |
| Dielectric substrate: | 0.100 mm |
| Carrier material / Aluminium: | 1.5 mm |

Optional: It is possible to have depth milling, drills with threads (extra charge applies).
 This data must be supplied in a separate DXF or Target Frontpanel Designer file.

